

SYMPOSIUM PROGRAM

Thin film engineering for photovoltaics, photonics and optoelectronics

Wednesday 28.09.2022

TIME	TOPIC	LECTURER	INSTITUTION
8:30 - 9:15	Registration	-	-
9:15 - 9:30	Inauguration	Tomasz Szablewski Prof. Maria Kamińska	TECHNOLUTIONS, UNIWERSYTET WARSZAWSKI
9:30 - 10:15	Spin coating – an introduction to a common methodology and its hidden difficulties	Tom Trowles	LAURELL TECHNOLOGIES CORPORATION
10:15 - 10:45	Advanced coatings for industrial applications by Atomic Layer Deposition	Kalle Niiranen	BENEQ OY
10:45 - 11:00	Digital Holography Microscope (DHM): principle and applications	Patryk Nienąłtowski	POLITECHNIKA WARSZAWSKA LYNCÉE TEC
11:00 - 11:20	Laboratory scale physical vapour deposition processes	Colin Moorhouse	MOORFIELD NANOTECHNOLOGY LIMITED
11:20 - 12:00	Coffee Break	-	-
12:00 - 12:30	ALD – PECVD – ICP PECVD comparison	Andreas Stamm	OXFORD INSTRUMENTS
12:30 - 13:00	Thin Film & Solar Energy applications: from Lab Scale to Large Area	Paola Santilli	KENOSISTEC SRL
13:00 - 13:45	Zastosowanie metod próżniowych do wytwarzania ogniw cienkowarstwowych CIGS	Andrzej Mischczuk	ROLTEC SP. Z O. O.
13:45 - 14:40	Lunch	-	-
14:40 - 15:00	2D materials using CVD Technology	Colin Moorhouse	MOORFIELD NANOTECHNOLOGY LIMITED
15:00 - 15:20	To be defined	Pavel Komarov	NenoVision s.r.o.
15:30 - 17:00	Poster Session	-	-
19:30 - 00:00	Dinner	-	-

Thursday 29.09.2022

TIME	TOPIC	LECTURER	INSTITUTION
9:00 - 9:30	ALE Atomic Layer Etching vs RIE and ICP RIE	Andreas Stamm	OXFORD INSTRUMENTS
9:30 - 10:15	Wet chemical processing – a better method, and the benefits it offers	Tom Trowles	LAURELL TECHNOLOGIES CORPORATION
10:15 - 10:45	Profiler Technologies for thin-film characterisation	Daniel Mandic	KLA INSTRUMENTS GROUP
10:45 - 11:10	Electrical and optical characterization of Transparent conductive oxide from R&D to production.	Christophe Defranoux	SEMILAB
11:10 - 11:30	Coffee Break	-	-
11:30 - 11:45	Advanced 3D Microfabrication Techniques for High-Tech Applications	Deividas Andriukaitis	Femtika
11:45-12:15	Vistec's variable shaped electron-beam lithography systems: technology and applications	Mathias Haedrich	Vistec
12:15 - 12:40	SEMILAB off line and in line Metrology on silicon and thin film PV	Christophe Defranoux	SEMILAB
12:40 - 13:25	High lateral resolution and microscopic mapping - thin film characterization by Imaging Ellipsometry	Peter Thiensen	ACCURION GmbH
13:25-14:30	Lunch	-	-
14:30 - 15:00	Mechanical characterization of thin films by 3D profilometry and scratch testing in semiconductor industries	Philippe Kempe	RTEC-INSTRUMENTS SA
15:00 - 15:45	Surface a thin films 4D characterization by DHM	Patryk Nienałtowski	POLITECHNIKA WARSZAWSKA LYNCÉE TEC
15:45 - 16:15	Thin-Film thickness measurements using optical and electrical technologies	Daniel Mandic	KLA INSTRUMENTS GROUP
16:15 - 16:35	New imaging Metrology characterization applied to Optoelectronic devices like LED, microLED, and OLED	Christophe Defranoux	SEMILAB
16:35 - 17:00	The End / Certificates	Tomasz Szablewski	TECHNOLUTIONS